

Session 3 Microhandling

A New Approach for a Microparts Feeding System based on Inertial Force

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Design and Kinematic Analysis of 6 DOF Precision Aligner for Micro-Assembly

Y. Yoo, M. Lee, S. Lee, M. Hong. *Ajou University, Korea*; J. Song, C. Lee. *Korea Institute of Machinery & Materials (KIMM), Korea.*

Characterization, Optimization and Control of a Mobile Platform

D. Jasper, C. Edeler. *University of Oldenburg, Germany.*

Modular Robotic Platform for Silicon Micromechanical Assembly

D. Heriban, M. Gauthier, D. Gendreau. *FEMTO-ST Institute, France.*

Automation Software Architectures for Robotic Microhandling

Q. Zhou. *Northwestern Polytechnical University, China*; V. Sariola. *Helsinki University of Technology, Finland.*

Development of Micro-spindle System with the Tool Clamping Device using a Shape Memory Alloy and In-process Runout Monitoring System

W. Shim, H. Park, S. Ro, J. Park. *Korea Institute of Machinery & Materials (KIMM), Korea.*